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1. (Currently Amended) A socket for interconnecting a chip to a substrate, where the chip includes pads thereon and the substrate includes leads extending upwardly therefrom and are profiled to contact the pads, the socket comprising a housing having an upper chip receiving face, a lower substrate receiving face, and a plurality of longitudinally extending slots extending between said upper chip receiving face and said lower substrate receiving face, said socket including at least one resilient arm extending downwardly therefrom for contacting the substrate~~.~~ , the resilient arm being resilient in a direction generally perpendicular to said lower substrate receiving face, to allow resilient movement of the substrate towards and away from the lower substrate receiving face.

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2. (Original) The socket of claim 1, wherein said housing includes marginal side walls and marginal end walls, with said longitudinally extending slots being formed by ribs extending between said end walls.

3. (Currently Amended) The socket of claim ~~1~~ 2, wherein said at least one resilient arm extends from one of said marginal side walls.

4. (Original) The socket of claim 3, further comprising a pair of resilient arms along said one side marginal wall.

5. (Original) The socket of claim 4, further comprising a post attached to each of said marginal side walls, and resilient arms extending therefrom.

6. (Original) The socket of claim 5, wherein said resilient arms extend parallel to said marginal side walls.

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7. (Original) The socket of claim 5, wherein each said resilient arm includes a foot portion adjacent to a free end of each said arm, said foot portion having a lower surface, which is resiliently movable from a first free state position below said lower substrate receiving face to a resiliently deformable position planar with said lower substrate receiving face.

8. (Original) The socket of claim 7, wherein each said foot portion includes a substrate retaining member.

9. (Original) A socket for interconnecting a chip to a printed circuit board, where the chip includes pads thereon, said socket comprising:

a housing having an upper chip receiving face, a lower substrate receiving face, and a plurality of lead receiving openings extending between said upper chip receiving face and said lower substrate receiving face;

a substrate having a plurality of leads extending upwardly therefrom and positioned within said lead receiving openings, with contact ends of said leads positioned below said chip receiving face; and

a resilient spacer positioned between said substrate and said housing, said spacer being deformable to a position where said leads extend through said chip receiving face.

10. (Original) The socket of claim 9, wherein said spacer is comprised of at least one resilient arm extending downwardly therefrom for contacting the substrate.

11. (Original) The socket of claim 10, wherein said housing includes marginal side walls and marginal end walls, and said lead receiving openings are defined as longitudinally extending slots extending between said end walls.

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12. (Currently Amended) The socket of claim ~~9~~ 11, wherein said resilient spacer is defined as a resilient arm extending from one of said marginal side walls.

13. (Original) The socket of claim 12, further comprising a pair of resilient arms along said one side marginal wall.

14. (Original) The socket of claim 13, further comprising a post attached to each of said marginal side walls, and resilient arms extending therefrom.

15. (Original) The socket of claim 14, wherein said resilient arms extend parallel to said marginal side walls.

16. (Original) The socket of claim 14, wherein each said resilient arm includes a foot portion adjacent to a free end of each said arm, said foot portion having a lower surface, which is resiliently movable from a first free state position below said lower substrate receiving face to a resiliently deformable position planar with said lower substrate receiving face.

17. (Original) The socket of claim 16, wherein each said foot portion includes a substrate retaining member.

18. (Original) The socket of claim 17, wherein said substrate has a lead contact field and openings along side marginal edges thereof, and said substrate retaining members comprises posts interferingly positioned within said openings.

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19. (Original) The socket of claim 9, wherein said housing includes marginal side walls and marginal end walls, and said upper chip receiving face is defined by a recess into said housing defining inner peripheral edges in said marginal side walls and marginal end walls.

20. (Original) The socket of claim 19, further comprising locating members positioned adjacent said recess for positioning said chip in said housing in juxtaposition with said leads.